TLE4294GV50

Low Drop Out Voltage Regulator

Automotive Power



Never stop thinking



Low Drop Out Voltage Regulator

TLE4294GV50



1 Overview

Features

- Output voltage tolerance $\leq \pm 4\%$
- Very low drop out voltage
- Output current: 30 mA
- Low quiescent current consumption
- Wide operation range: up to 45 V
- Wide temperature range: T_i = -40 °C to +150 °C
- · Output protected against short circuit
- Overtemperature protection
- Reverse polarity protection
- Very small SMD-Package PG-SCT595-5
- Green Product (RoHS compliant)
- AEC Qualified

Description

The TLE4294 is a monolithic integrated low drop out voltage regulator in the very small SMD package PG-SCT595-5. It is designed to supply e.g. microprocessor systems under the severe conditions of automotive applications. Therefore, the device is equipped with additional protection functions against overload, short circuit and reverse polarity. At overtemperature the regulator is automatically turned off by the integrated thermal protection circuit.

Input voltages up to 40 V are regulated to $V_{Q,nom}$ = 5.0 V. The output is able to drive a load of more than 30 mA, while it regulates the output voltage within a 4% accuracy.

Туре	Package	Marking
TLE4294GV50	PG-SCT595-5	F1

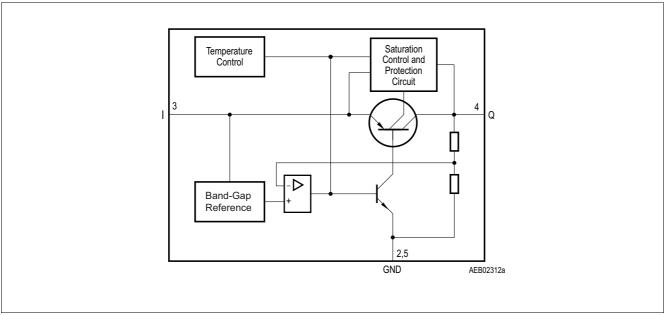


PG-SCT595-5



Block Diagram

2 Block Diagram





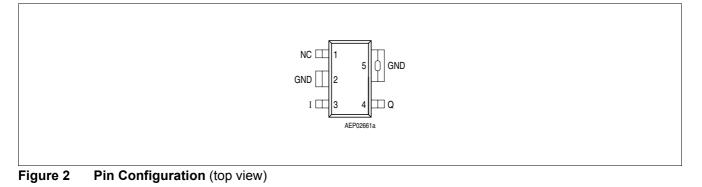
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Pin Configuration

3 Pin Configuration

3.1 Pin Assignment



3.2 Pin Definitions and Functions

Table 1 Pin Definitions and Functions

Pin No.	Symbol	Function
1	N.C.	Not connected Internally not connected. Connect to GND
2	GND	Ground reference Connected to pin 5
3	1	Input voltage For compensating line influences, a capacitor to GND close to the IC terminals is recommended
4	Q	Output voltageBlock to GND with a capacitor close to the IC terminals, respecting the valuesgiven for its capacitance CQ and ESR in the Table 4.2 "Functional Range" onPage 5 (Tantalum capacitor recommended as output capacitor)
5	GND	Ground reference Connect to heatsink area; Connected to pin 2



4 General Product Characteristics

4.1 Absolute Maximum Ratings

Absolute Maximum Ratings ¹⁾

 T_j = -40 °C to +150 °C, all voltages with respect to ground, direction of currents as shown in **Figure 3 "Application Circuit" on Page 7** (unless otherwise specified)

Pos.	Parameter	Symbol	Lim	it Values	Unit	Conditions
			Min.	Max.		
Input	-			 		
4.1.1	Voltage	V_1	-42	45	V	-
4.1.2	Current	I	-	-	mA	Internally limited
Output	:			Į		
4.1.3	Voltage	V _Q	-6	30	V	-
4.1.4	Current	IQ	_	-	mA	Internally limited
Tempe	ratures	I				
4.1.5	Junction temperature	Tj	-40	150	°C	_
4.1.6	Storage temperature	T _{stg}	-50	150	°C	_
ESD Su	usceptibility					
4.1.7	ESD Resistivity	V_{ESD}	-2	2	kV	HBM ²⁾
4.1.8	ESD Resistivity to GND	V _{ESD}	-750	750	V	CDM ³⁾

1) Not subject to production test, specified by design.

2) ESD susceptibility, Human Body Model "HBM" according to EIA/JESD 22-A114B

3) ESD susceptibility, Charged Device Model "CDM" according to EIA/JESD22-C101 or ESDA STM5.3.1

Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

4.2 Functional Range

Pos.	Parameter	Symbol	Lir	nit Values	Unit	Conditions
			Min.	Max.		
4.2.1	Input Voltage	V ₁	5.5	45	V	-
4.2.2	Output Capacitor Requirements	CQ	2.2	_	μF	-
4.2.3		ESR _{CQ}	1.5	8	Ω	1)
4.2.4	Junction Temperature	Tj	-40	150	°C	-

1) Equivalent series resistance measured at a frequency of 10 kHz

Note: Within the functional range the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the related electrical characteristics table.



General Product Characteristics

4.3 Thermal Resistance

Pos.	Parameter	Symbol	I	Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
4.3.1	Junction to Ambient ¹⁾	R _{thJA}	-	179	_	K/W	Footprint only ²⁾
4.3.2			-	99	-	K/W	300mm ² heatsink area on PCB ²⁾
4.3.3			-	87	-	K/W	600mm ² heatsink area on PCB ²⁾
4.3.4			-	80	-	K/W	2s2p PCB ³⁾
4.3.5	Junction to Soldering Point ¹⁾	R _{thJSP}	-	26	-	K/W	Measured to pin 5

1) Not subject to production test, specified by design

2) EIA/JESD 52_2, FR4, 80 \times 80 \times 1.5 mm; 35 μ Cu, 5 μ Sn

 Specified R_{thJA} value is according to JEDEC JESD51-2,-5,-7 at natural convection on FR4 2s2p board; The product (chip+package) was simulated on a 76.2 x 114.3 x 1.5 mm board with 2 inner copper layers (2 x 70µm Cu, 2 x 35µm Cu).



Electrical Characteristics

5 Electrical Characteristics

Table 2 Electrical Characteristics

 V_1 = 13.5 V, T_j = -40 °C to +150 °C, all voltages with respect to ground, direction of currents as shown in **Figure 3** "Application Circuit" on Page 7 (unless otherwise specified)

Pos.	Parameter	Symbol		Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
Output		1		1	1		l
5.0.1	Output voltage	V _Q	4.80	5.00	5.20	V	1 mA < I_Q < 30 mA V_I = 13.5 V
5.0.2	Output voltage	V _Q	4.80	5.00	5.20	V	$I_{\rm Q}$ = 10 mA 6 V < $V_{\rm I}$ < 40 V
5.0.3	Output current limitation	IQ	30	-	_	mA	1)
5.0.4	Drop out voltage	V_{dr}	-	0.25	0.40	V	$I_{\rm Q}$ = 20 mA ¹⁾
Curren	t Consumption		•	<u> </u>		·	
5.0.5	Current consumption $I_{q} = I_{1} - I_{Q}$	Iq	_	2	4	mA	I _Q < 30 mA
5.0.6	Current consumption $I_q = I_1 - I_Q$	Iq	-	120	200	μA	<i>I</i> _Q < 1 mA
Regula	tor Performance						
5.0.7	Load regulation	$ \Delta V_{Q} $	_	10	25	mV	1 mA < I _Q < 25 mA; T _j = 25 °C
5.0.8	Load regulation	$ \Delta V_{Q} $	-	10	30	mV	1 mA < I _Q < 25 mA
5.0.9	Line regulation	$ \Delta V_{Q} $	-	5	25	mV	$\Delta V_{\rm l} = V_{\rm l, min} \text{ to 36 V};$ $I_{\rm Q} = 5 \text{ mA};$ $T_{\rm j} = 25 \text{ °C}$
5.0.10	Line regulation	$ \Delta V_{\rm Q} $	-	10	30	mV	$\Delta V_{\rm I} = V_{\rm I, min}$ to 36 V; $I_{\rm Q} = 5$ mA
5.0.11	Power Supply Ripple Rejection P		_	60	-	dB	$f_{\rm r}$ = 100 Hz; $V_{\rm r}$ = 0.5 Vpp

1) Measured when the output voltage $V_{\rm Q}$ has dropped 100 mV from its nominal value.

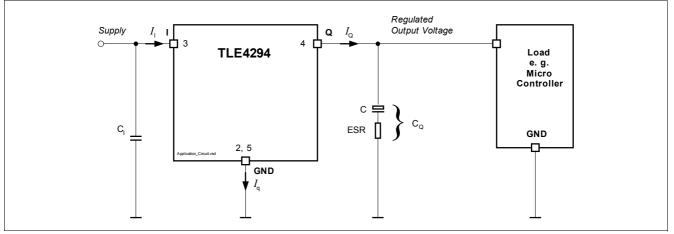


Figure 3 Application Circuit



Package Outlines

6 Package Outlines

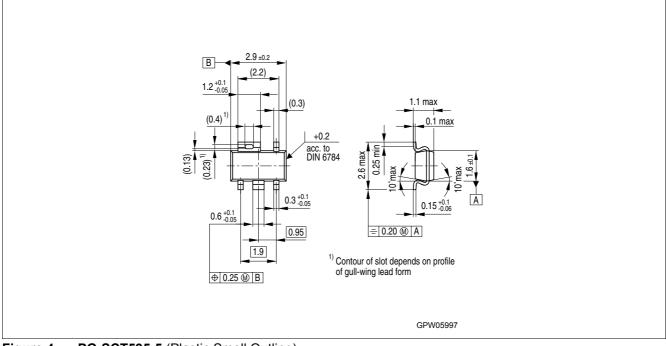


Figure 4 PG-SCT595-5 (Plastic Small Outline)

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

For further information on alternative packages, please visit our website: http://www.infineon.com/packages.

Dimensions in mm

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Revision History

7 Revision History

Revision	Date	Changes
1.1	2008-02-26	Device marking changed to F1
1.0	2007-08-10	Initial Data sheet

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